

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re application of:

TONGBI JIANG

Serial No.:

EXAMINER:

Filing Date: 10/15/2003

Division of Serial No. 10/178,703  
filed 06/24/2002

Art Unit:

For: No Flow Underfill Material And Method  
For Underfilling Semiconductor Components

Attorney Docket No. 01-0219.1

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**PRELIMINARY AMENDMENT  
SUBMITTED WITH CONTINUING APPLICATION  
UNDER 37 CFR 1.53(b)**

**OCTOBER 15, 2003**

Mail Stop Patent Application  
Commissioner of Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

This Preliminary Amendment is being filed with a divisional application under 37 CFR 1.53(b). Please amend the captioned case as follows.